	REVISIONS		
LTR	DESCRIPTION	DATE	APPROVED
D	Change max frequency C _L = 15 pF subgroups 10 and 11. Change max frequency C _L = 50 pF subgroups 10 and 11. Change code ident. no. to 67268. Change to military drawing format. Add CAGE 01295 for case outline S and 2.	6 NOV. 1987	PPErans

CURRE	NT	CA	١G	ìΕ	C	0	DE	E 6	372	26	8														
REV		\Box																							
PAGE																			Ш	Ц					
REV STATUS	REV		D	۵	٥	D	۵	D	D	Θ	ם	D	۵												
OF PAGES	PAG	ES	1	2	3	4	5	6	7	8	9	10	11												
Defense Electro Supply Center Dayton, Ohio	onics		L	7	DA			•	4		y		Th all	is c	iraw parti	ing men	is a	vaile	able Agen	for	use	by	<u> </u>	10	;
Original date of drawing:					RO	XEI		<u>へ</u>	5	J.			TI	TLE Fi	: MI SC LOP	CRO HOT WIT	CIR TKY H C	CUIT TTL LEAR	, DI , OC	GIT CTAL ONOL	AL, D-	LOV TYPE IC S	N PO E FL SILI	WER IP CON	i
7 December 1	978			SIZ	E	C	ODE	_	DEN 3	_ `	NO		ρĭ	WG	N	5 .	7	78	0	IC)				
AMSC N/A			Γ	REV	,		D							P	AG	E	1		0	F		11			
										7											5	962-	-E59	0	

DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

DESC FORM 193

MAY 86

Powered by ICminer.com Electronic-Library Service CopyRight 2003

1. SCOPE				
1.1 Scope. This drawing describes de $1.2.1$ of MIL-STD-883, "Provisions for the devices".	evice requirement ne use of MIL-S	nts for class TD-883 in con	B microcircuits in unction with compli	accordance with ant non-JAN
1.2 Part number. The complete part	number shall be	as shown in t	the following exampl	e:
Drawing number Device	ce type	R 	X - - 	
1.2.1 Device type. The device type	shall identify	the circuit fu	unction as follows:	
Device type Generic r	umber	Circuit fund	tion	
01 54LS2	.73 Octal	D-type, flip	flop with clear	
1.2.2 <u>Case outlines</u> . The case outline follows:	es shall be as	designated in	appendix C of MIL-	M-38510, and as
Outline letter		Case outline		
R S 2	D-8 (20-lead F-9 (20-lead C-2 (20-term	, 1/4" x 1 1/1 , 1/4" x 1/2") inal, .350" x	6"), dual-in-line p , flat package .350"), square chip	ackage carrier package
1.3 Absolute maximum ratings.				
Supply voltage range Input voltage range Storage temperature Maximum power dissipation (P _D) 1/Lead temperature (soldering, 10 se Thermal resistance, junction-to-ca Junction temperature (T _J) 1.4 Recommended operating conditions.		1. 65 19 +30 See	"C to +150"C mW 0"C MIL-M-38510, append	
Supply voltage (V_{CC}) Minimum high level input voltage (Max.imum low level input voltage (V Case operating temperature range (Clock frequency, (F clock) High level output current, (I_{OH}) - Low level output current, (I_{OL}) - Width of clock or clear pulse (Tw) Setup time (tsu) Data input Clear to inactive state Data hold time (t_n)	IC) IT)	2.0 0.7 55 0 to 4 mu 30 i	V dc	5.5 V dc maximum
1/ Must withstand the added P _D due to si	nort circuit te	est (e.g., I _{OS})		
MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER	SIZE A		DWG NO 78010	
DAYTON, OHIO		REV D	PAGE	2

PAGE

2



2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510

Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883

Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

- 2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.
 - 3. REQUIREMENTS
- 3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- 3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
 - 3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.
 - 3.2.2 Truth table. The truth table shall be as specified on figure 2.
 - 3.2.3 Logic diagram. The logic diagram shall be as specified on figure 3.
 - 3.2.4 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.
- 3.3 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full recommended case operating temperature range.
- 3.4 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in 6.4 herein.
- 3.5 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in 6.4. The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall state that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.6 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.

MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER	SIZE			DWG NO	78010		
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO		REV	D		PAGE	3	

-		
	٠	

	Υ	TABLE I. EI									
Test	Symbol	-55	Cor C < T ₍ ess oth	nditio C <u><</u> +l	ns 25°C,	l filad		Group A		imits	Uni
	 				spec	- I leu		subgroup	S Min	Max	
High level output voltage	V _{OH}	V _{CC} = 4.5 V; I _{OH} = -400 µ V _{IN} = 0.7 V	A or 2.0	٧				1, 2, 3	2.5	5	\
Low level output voltage	V _{OL}	V _{CC} = 4.5 V; I _{OL} = 4 mA V _{IN} = 0.7 V	or 2.0	V				1, 2, 3		0.4	V
Input clamp voltage	V _{IC}	V _{CC} = 4.5 V; T _C = +25 °C		I _{IN} :	-18	mA ;		1		-1.5	 V
High level input current	I _{IH1}	V _{CC} = 5.5 V;		VIN :	- 5.5	٧		1, 2, 3		0.1	mA
	I IH2	V _{CC} = 5.5 V;		V _{IN} :	2.7	٧		1, 2, 3	 	20	<u>μ</u> Α
ow level input current	IIL	V _{CC} = 5.5 V;		V _{IN} =	0.4	v		1, 2, 3		-0.4	l mA
Short circuit output current	Ios	V _{CC} = 5.5 V	1/	<u>-</u>	·			1, 2, 3	-15	-130	I mA
Supply current	Icc	V _{CC} = 5.5 V	<u>2</u> /					1, 2, 3		27	mA
unctional tests		 See 4.4.1c						7			<u> </u>
laximum clock frequency 3/	FMAX	 Y _{CC} = 5.0 Y R _L = 2 kΩ ±5% 		CL ≈	15 pł	±10%		9	30		MH2
				 				10, 11	18		MHZ
 				CL =	50 pF	±10%		9	24		MHz
							 	10, 11	17		MHz
ee footmotes at en	d of tab	le.								<u>-</u>	
MILITARY DEFENSE ELECTRON	IICS SUP		SIZE		-			DWG NO	78010		
DAYTO	N, OHIO	_	[R	ΕV	D	ļ	PAGE	4	

Test	Symbol	-55°C <	onditions T _{C ≤} +125°C, herwise specified	Group A	Lin	i ts	Unit
		unless öt	herwise specified	subgroups	Min	Max	†
Propagation delay time, high to low, clear to	t _{PHL1}	V _{CC} = 5.0 V R _L = 2 kΩ ±5%	C _L = 15 pF *10%	9		27	ns
output <u>3</u> /				10, 11		38	ns
		 	C _L = 50 pF ±10%	9		32	ns
		<u> </u> - -	 	10, 11		42	ns
Propagation delay time, low to high, clock to	tpLH	 - - -	C _L = 15 pF ±10%	9		27	ns
output 3/				10, 11		38	ns
	 	 	C _L = 50 pF ±10%	9	i	32	ns
	<u> </u> 			10, 11		42	ns
Propagation delay time, high to low, clock to	 tp _{HL2} 	- 	C _L = 15 pF ±10%	9		27	l ns
output 3/				10, 11		38	ns
	 	 	C _L = 50 pF ±10%	9		32	ns
] [10, 11		42	ns

^{1/} Not more than one output should be shorted at a time, and the duration of the short circuit condition should not exceed 1 second.

MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER	SIZE A			DWG NO	78010		-
DAYTON, OHIO		REV	D		PAGE	5	

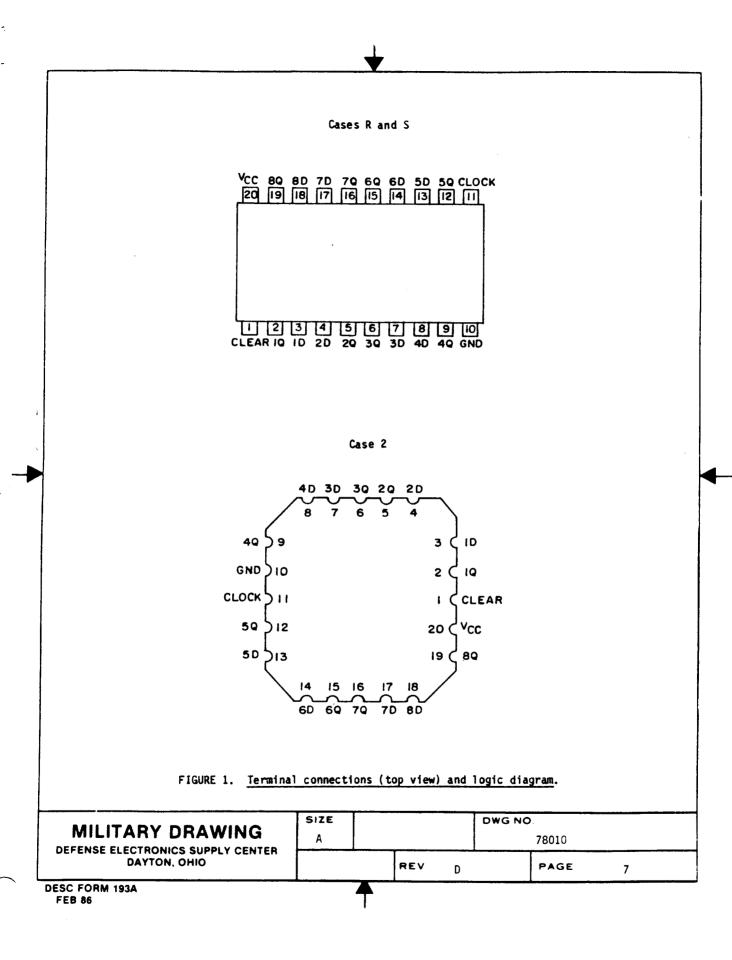
 $[\]frac{2}{}$ With all outputs open and 4.5 V applied to all data and clear inputs, I_{CC} is measured after a momentary ground, then 4.5 V is applied to clock.

 $[\]frac{3}{C_L}$ Propagation delay time and maximum clock frequency testing may be performed using either C_L = 15 pF or C_L = 50 pF. However, the manufacturer must certify and guarantee that the microcircuits meet the test limits specified for a 50 pF load.



- 3.8 Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
 - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test (method 1015 of MIL-STD-883).
 - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
 - 4.3.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 4, 5, 6, and 8 in table I, method 5005 of MIL-STD-883 shall be omitted.
 - c. Subgroup 7 tests shall verify the truth table.
 - 4.3.2 Groups C and D inspections.
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test (method 1005 of MIL-STD-883) conditions:
 - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by appendix B of MIL-M-38510 and method 1005 of MIL-STD-883.

MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER	SIZE A	*		DWG NO	78010		
DAYTON, OHIO		REV	D		PAGE	6	



(Each flip flop) Inputs Output Clear clock D L X X L Н н Н Н L L Н X Q_0 H = High level (steady state) L = Low level (steady state) X = Don't care ♠ = Low to high transition Q_0 = The level of Q before the indicated steady state input conditions were established FIGURE 2. Truth table. SIZE DWG NO **MILITARY DRAWING** Α 78010 DEFENSE ELECTRONICS SUPPLY CENTER

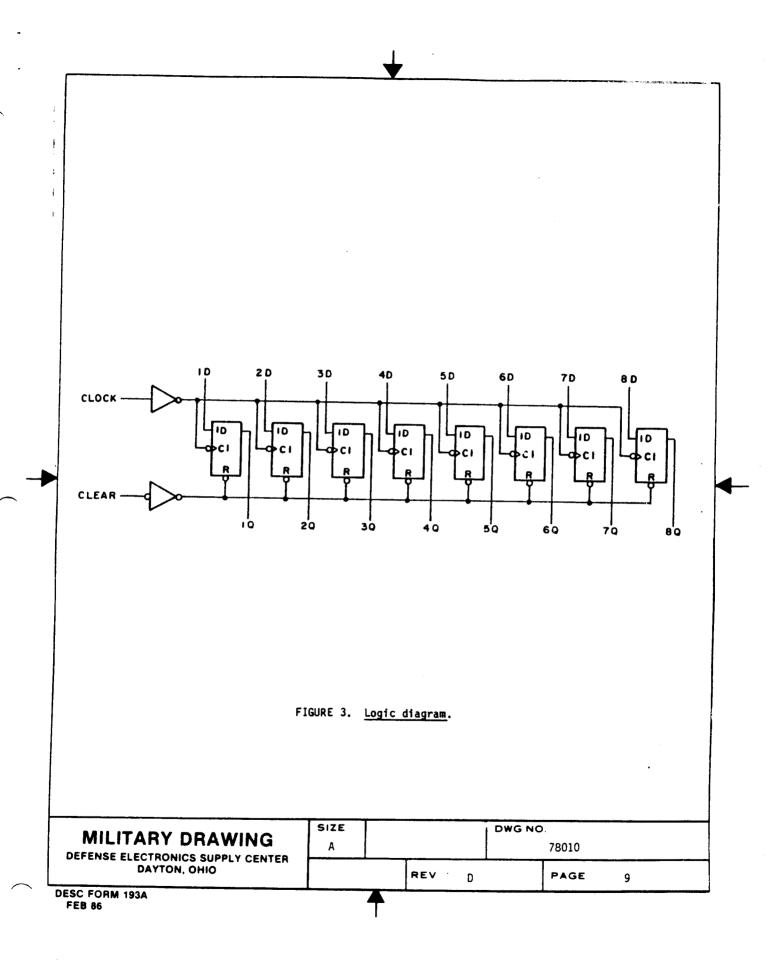
REV

D

PAGE

8

DAYTON, OHIO





MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	
Final electrical test parameters (method 5004)	1*, 2, 3, 9
Group A test requirements (method 5005)	1 1, 2, 3, 7, 9 10, 11
Groups C and D end point electrical parameters (method 5005)	1, 2, 3

^{*} PDA applies to subgroup 1.

- 5. PACKAGING
- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.
- 6. NOTES
- 6.1 <u>Intended use.</u> Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
 - 6.2 Replaceability. Replaceability is determined as follows:
 - a. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
 - b. When a QPL source is established, the part numbered device specified in this drawing will be replaced by the microcircuit identified as part number M38510/32501B--.
- 6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.

MILITARY DRAWING	SIZE		-	DWG NO	78010	
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO		REV	D	1	PAGE	10

6.4 Approved sources of supply. Approved sources of supply are listed herein. Additional sources will be added as they become available. The vendors listed herein have agreed to this drawing and a certificate of compliance (see 3.5 herein) has been submitted to DESC-ECS.

Military drawing part number	Vendor CAGE number	Vendor 2/ similar part number	Replacement military specification part number
7801001RX 1/	18324 04713 01295	54LS273/BRA 54LS273/BRAJC SNJ54LS273J	M38510/32501BRX
78010015X <u>1</u> /	18324 04713 01295	54LS273/BSA 54LS273/BSAJC SNJ54LS273W	 M38510/32501BSX
78010012X <u>1</u> /	18324 04713 01295	54LS273/B2X 54LS273M/B2CJC SNJ54LS273FK	 M38510/32501B2X

Vendor CAGE number	Vendor name and address		
18324	Signetics Corporation 4130 South Market Court Sacramento, CA 95834		
04713	Motorola, Incorporated 7402 S. Price Road Tempe, AZ 85283		
01295	Texas Instruments, Incorporated P.O. Box 6448 Midland, TX 79701		

MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE	DWG NO 78010		
		REV D	PAGE	11